

4.0x4.0mm RIGHT ANGLE SURFACE MOUNT LED LAMP

KA-4040SURC

HYPER RED

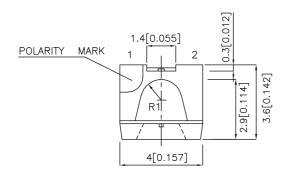
Features

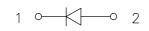
- •SINGLE COLOR.
- •SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- •AVAILABLE ON TAPE AND REEL.
- •IDEAL FOR BACKLIGHTING.
- ●PACKAGE: 500PCS / REEL.
- ●RoHS COMPLIANT.

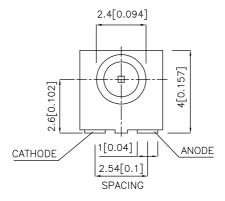
Description

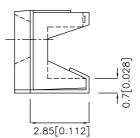
The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions









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Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

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APPROVED: J. Lu CHECKED: Allen Liu DRAWN: W.J.ZHU

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Selection Guide

Part No.	Dice	Dice Lens Type Iv (mcd) @ 20mA		,	Viewing Angle
			Min.	Тур.	201/2
KA-4040SURC	HYPER RED (InGaAIP)	WATER CLEAR	70	200	90°

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	I==20mA
λD	Dominant Wavelength	Hyper Red	628		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	27		nm	IF=20mA
С	Capacitance	Hyper Red	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Red	1.9	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

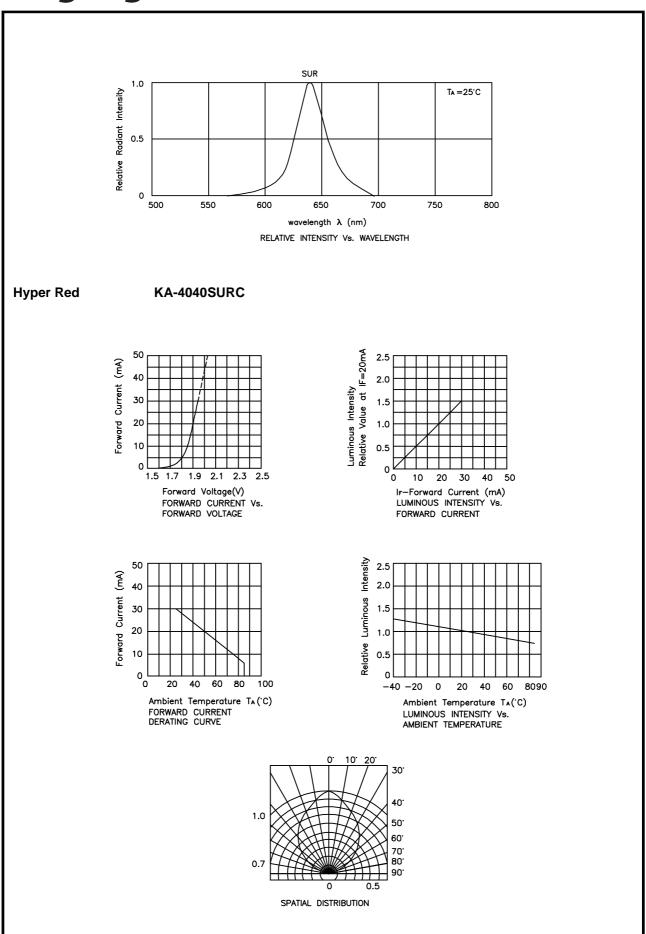
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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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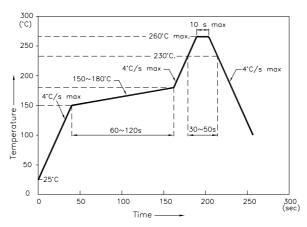
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Reflow Soldering Profile For Lead-free SMT Process.

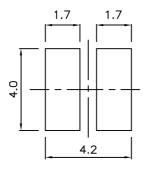


NOTES

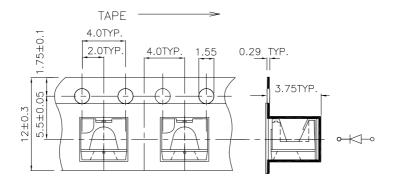
- We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage,luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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